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Application Number	10/809,867
Filing Date	March 26, 2004
First Named Inventor	Masanori UEDA et al.
Art Unit	3729
Examiner Name	Anthony D. Tugbang
Attorney Docket Number	025720-00027

Sheet	1	of	1
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**U.S. PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Document Number	Number-Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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**FOREIGN PATENT DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Foreign Patent Document	Country Code <sup>3</sup>	Number-Kind Code <sup>2</sup> (if known)	Publication Date MM-DD-YYYY	Name of Patentee or Applicant of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sup>4</sup>
/ADT/		2001-060846	JP	A	03-06-2001	MATSUSHITA ELECTRIC IND CO. LTD.		AB
		9-008595	JP	A	01-10-1997	MATSUSHITA ELECTRIC IND CO. LTD.		AB
		2001-060658	JP	A	03-06-2001	ROHM CO. LTD.		AB
		2001-332654	JP	A	11-30-2001	MATSUSHITA ELECTRIC IND. CO. LTD.		AB
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		2002-184960	JP	A	06-28-2002	SHINETSU HANDOTAI KK		AB
/ADT/								

**NON PATENT LITERATURE DOCUMENTS**

Examiner Initials*	Cite No. <sup>1</sup>	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T <sup>4</sup>
/ADT/		Hideki TAKAGI, "Room-Temperature Bonding of Silicon Wafers by means of the Surface Activation Method" Report of Mechanical Engineering Laboratory No. 189, December 2000, Pages 1-7, and 68-84.	AB

Examiner Signature	/A. Dexter Tugbang/	Date Considered	5/24/07
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant. <sup>1</sup>Unique citation designation number. <sup>2</sup>See attached Kinds of U.S. Patent Documents. <sup>3</sup>Enter Office that issued the document, by the two-letter code. <sup>4</sup>For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup>Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup>Applicant is to place a check mark here if English language translation is attached. AB indicates that only an English language abstract is attached.

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